[News] Mapping the Micro LED Optical Interconnect Ecosystem

[新闻] 绘制 Micro LED 光互连生态系统图谱

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As AI data centers continue to scale, power consumption and bandwidth bottlenecks are becoming increasingly critical. To address these challenges, Micro LED optical interconnect technology is emerging as a key solution.

随着 AI 数据中心的持续扩张，芯片间互连的功耗与带宽瓶颈正变得日益关键。为应对这一挑战，Micro LED 光互连技术正成为一种重要的解决方案。

By replacing traditional high-speed serial architectures with parallel optical transmission, Micro LED can support data rates of 2 Gbps per channel or higher. Its low-latency and low-power characteristics make it well-suited for short-reach, high-density interconnect applications.

通过将传统高速串行架构替换为并行光传输，Micro LED 可支持每通道 2 Gbps 或更高的数据速率。其低延迟、低功耗特性，使其非常适合短距离、高密度互连应用。

Currently, Micro LED arrays can integrate more than 960 channels, with a pitch as small as 3.5 µm. Combined with CMOS driver ICs, they can support transmission rates of 1.2 Tbps or higher, while maintaining a power consumption of less than 0.1 pJ/bit.

目前，Micro LED 阵列可集成 960 个以上通道，像素间距最小可达 3.5 µm。结合 CMOS 驱动 IC，其传输速率可达 1.2 Tbps 以上，同时功耗保持在 0.1 pJ/bit 以下。

This architecture eliminates the need for several power-hungry components, including DSPs, SerDes, and TIA/LDs—reducing energy consumption to just 1 pJ/bit, which is only one-tenth that of traditional VCSEL solutions required to create cable assemblies.

该架构无需多个高功耗组件，包括 DSP、SerDes 和 TIA/LD，将能耗降低至仅 1 pJ/bit，仅为传统 VCSEL 方案的十分之一，后者还需要额外制作线缆组件。

Although transmission distances are currently limited to under 10 meters, Micro LED can still meet the bandwidth requirements of most intra-rack or inter-rack scenarios. It can also be flexibly integrated with existing copper or fiber DAC/AOC cable assemblies.

虽然传输距离目前限制在 10 米以内，但 Micro LED 仍可满足大多数机架内或机架间场景的带宽需求，并可灵活集成现有铜缆或光纤 DAC/AOC 线缆组件。

Global Players Race to Define the Micro LED CPO Market

全球厂商竞相定义 Micro LED CPO 市场

The Micro LED CPO industry remains in an early stage, with ecosystem development and technology validation progressing simultaneously. Key specifications—including chip size, pitch, and driver IC architecture—have yet to be standardized, and no mass production timeline has been announced.

Micro LED CPO 产业仍处于早期阶段，生态系统发展与技术验证同步推进。关键规格——包括芯片尺寸、间距和驱动 IC 架构——尚未标准化，也未公布量产时间表。

To the best of our knowledge, only a few companies globally have successfully demonstrated Micro LED CPO prototypes. Among them, Microsoft's MOSAIC architecture has received significant attention for its unique approach to optical interconnects.

据我们所知，全球仅有少数几家公司成功展示了 Micro LED CPO 原型。其中，微软的 MOSAIC 架构因其独特的光互连方案而备受关注。

Microsoft's MOSAIC architecture leverages the optical transparency of silicon to enable direct optical coupling between optical fibers and Micro LED arrays, achieving an optical bandwidth density of 1 Tbps/mm² and a power consumption of just 0.35 pJ/bit. This approach eliminates the need for DSPs, SerDes, and TIA components, significantly reducing system power consumption and latency.

微软 MOSAIC 架构利用硅的光学透明性，实现光纤与 Micro LED 阵列之间的直接光耦合，达到 1 Tbps/mm² 的光带宽密度和仅 0.35 pJ/bit 的功耗。该方案无需 DSP、SerDes 和 TIA 组件，显著降低系统功耗与延迟。

The core architecture adopts a 3D stacked design: Micro LED chips are flip-bonded to the CMOS backplane, while optical fibers are inserted vertically into the backside of the silicon substrate. Light is coupled directly into the Micro LED arrays, significant differences remain in chip wavelength, optical power, and modulation speed.

核心架构采用 3D 堆叠设计：Micro LED 芯片倒装键合至 CMOS 背板，光纤则垂直插入硅基板背面。光直接耦合进入 Micro LED 阵列，但芯片在波长、光功率和调制速度上仍存在显著差异。

To overcome this, Microsoft developed DDP (Delicate Harvest To Mass Vision Device) to control the driving current of each pixel, ensuring consistent brightness and modulation speed across the array.

为克服这一问题，微软开发了 DDP（精细采集至大规模视觉设备），用于控制每个像素的驱动电流，确保整个阵列的亮度与调制速度一致。

In March 2025, Avicena signed a joint development agreement with one CSP. The partnership aims to integrate Avicena's LightBundle™ optical interconnect technology with a 200G/lane Micro LED array and CMOS driver IC, targeting a 1.6 Tbps optical engine for next-generation AI clusters.

2025 年 3 月，Avicena 与一家 CSP 签署了联合开发协议，旨在将其 LightBundle™ 光互连技术与 200G/lane Micro LED 阵列及 CMOS 驱动 IC 集成，面向下一代 AI 集群打造 1.6 Tbps 光引擎。

Meanwhile, Marvell, a leading supplier of optical interconnect solutions, has also entered the Micro LED CPO ecosystem, significant differences remain in chip wavelength, optical power, and modulation speed.

与此同时，光互连解决方案领先供应商 Marvell 也已进入 Micro LED CPO 生态系统的早期阶段，但在芯片波长、光功率和调制速度上仍存在显著差异。

China's Emerging Micro LED CPO Ecosystem

中国新兴的 Micro LED CPO 生态系统

Companies in Chinese Mainland and Taiwan have also begun to participate in the Micro LED CPO ecosystem.

中国大陆和台湾的企业也开始参与 Micro LED CPO 生态系统的建设。

In Chinese Mainland, participation has been more concentrated. Traditional CPO manufacturers are among the optical communications, while cross-industry collaborations are also emerging around new wavelength applications.

在中国大陆，参与者更为集中。传统 CPO 厂商是光通信领域的主要参与者，同时跨行业合作围绕新兴波长应用也开始出现。

Most projects remain in the sample development and validation stages, with no mass production timelines announced yet.

大多数项目仍处于样品开发与验证阶段，尚未公布量产时间表。

In Taiwan, companies are focusing on upstream segments, particularly Micro LED chip fabrication and driver IC design.

台湾企业则聚焦于上游环节，尤其是 Micro LED 芯片制造和驱动 IC 设计。

Among the most notable examples is AUO, which has established a dedicated Micro LED display business unit and is now targeting CPO applications. By adopting a glass RDL-based packaging approach, AUO aims to integrate Micro LED CPO without investing in their own mass production lines, leveraging its existing display manufacturing capabilities.

其中最引人注目的是友达光电（AUO），其已成立专门的 Micro LED 显示业务单位，并将目标锁定 CPO 应用。AUO 采用基于玻璃 RDL 的封装方案，旨在利用现有显示制造产能，无需自建量产线，即可集成 Micro LED CPO。

The company has already begun system-level CPO prototyping and is actively engaging with potential customers.

该公司已开始进行系统级 CPO 原型开发，并积极与潜在客户接洽。

PsiQuantum has also entered into cooperation with Brillink, a Micro LED display company, to develop a prototype for a wafer-level Micro LED CPO packaging platform.

PsiQuantum 也与 Micro LED 显示公司 Brillink 合作，开发晶圆级 Micro LED CPO 封装平台原型。

Additionally, Chunghwa Precision Test Tech. (CPTT) has begun developing Micro LED CPO testers, targeting mass production in 2027.

此外，中华精测（CPTT）已开始开发 Micro LED CPO 测试机台，目标 2027 年量产。

CPO Reshapes the Value Proposition of Micro LED CPO 重塑 Micro LED 的价值主张

Whether through vertical integration in Taiwan, cross-sector partnerships in Chinese mainland, or strategic collaborations in the U.S., the emerging Micro LED CPO ecosystem is taking shape. Although the technology still faces challenges in standardization and mass production, its potential in AI data centers is undeniable.

无论是通过台湾的垂直整合、中国大陆的跨领域合作，还是美国的战略联盟，新兴的 Micro LED CPO 生态系统正逐渐成形。尽管该技术仍面临标准化与量产挑战，其在 AI 数据中心的潜力不容忽视。

The key questions for the industry now lie in when market demand will reach a critical mass, when CPO ecosystems will become, and how Micro LED CPO will interact with the existing optical interconnect roadmap.

产业现在面临的问题不外乎是市场何时规模，生态系统何时成形，以及 Micro LED CPO 将如何与现有光互连路线图互动。

当光互连应用开始突破短距——而超越机架——Micro LED 的优势将变得更为明显。

When optical interconnects start to move beyond short reach—and beyond rack—Micro LED's advantages will become more pronounced.

Looking ahead, display and optical communication companies are expected to reinforce one another, creating a win-win scenario. TrendForce forecasts that the global Micro LED CPO market will reach $1.2 billion by 2030.

展望未来，显示与光通讯厂商预计将相互强化，形成双赢局面。TrendForce 预估，全球 Micro LED CPO 市场规模将于 2030 年达到 12 亿美元。

Shipments of Micro LED CPO optical transceiver modules are expected to begin ramping in the second half of 2027, with the market projected to reach approximately 1,000 units by 2030.

Micro LED CPO 光收发模块预计将于 2027 年下半年开始放量，市场预计 2030 年达到约 1,000 台。

Beyond enabling more efficient AI data center interconnects, Micro LED CPO is expected to create new opportunities in AR/VR, automotive, and IoT applications.

除了实现更高效的 AI 资料中心互连，Micro LED CPO 预计也将为 AR/VR、车用及 IoT 应用带来新机会。

Manufacturing capabilities developed for optical communication may also be leveraged in these fields.

光通讯领域所开发的制造能力，也有望应用于这些领域。

Looking further ahead, as Micro LED CPO matures, its role in computing and sensing is also worth watching.

展望更远，随着 Micro LED CPO 技术成熟，其在运算与感测领域的角色也值得关注。

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